

Multilayer Power Inductor

CIG2MW Series (2016/ EIA 0806)



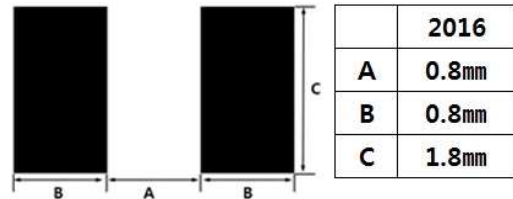
APPLICATION

Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

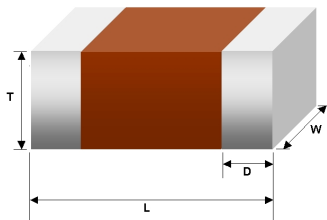
FEATURES

- Low Profile (1.0mm max)
- Excellent DC bias characteristic
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability

RECOMMENDED LAND PATTERN



DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
2M	2.0±0.15	1.6±0.15	0.9±0.1	0.5±0.2

DESCRIPTION

Part no.	Size (inch/mm)	Inductance (μ H)@1MHz	DC Resistance(Ω)	Rated Current (A) Max.
CIG2MWR47NNE	0806/2016	0.47 \pm 30 %	0.060 \pm 25 %	1.60
CIG2MW1R0NNE	0806/2016	1.0 \pm 30 %	0.085 \pm 25 %	1.40
CIG2MW1R5NNE	0806/2016	1.5 \pm 30 %	0.11 \pm 25 %	1.20
CIG2MW2R2NNE	0806/2016	2.2 \pm 30 %	0.11 \pm 25 %	1.20
CIG2MW3R3NNE	0806/2016	3.3 \pm 30 %	0.12 \pm 25 %	1.20
CIG2MW4R7NNE	0806/2016	4.7 \pm 30 %	0.14 \pm 25 %	1.10

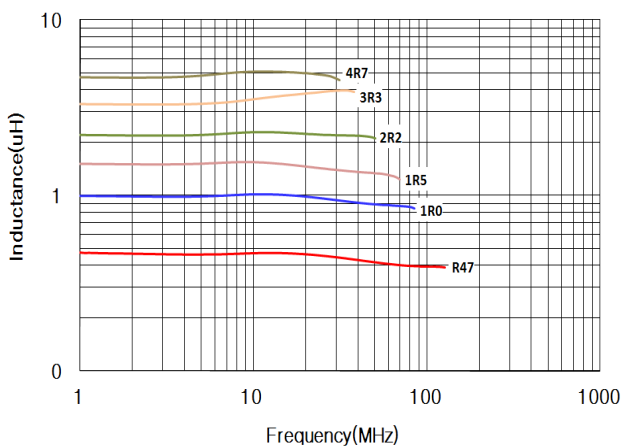
※Rated Current: DC current value when the self-generation of heat rises to 40°C (Reference ambient temperature:25°C)

※Operating temperature range: -40 to +125°C (Including self-temperature rise)

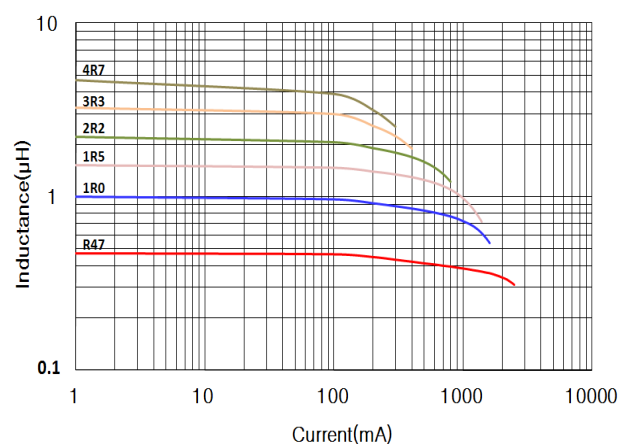
※Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



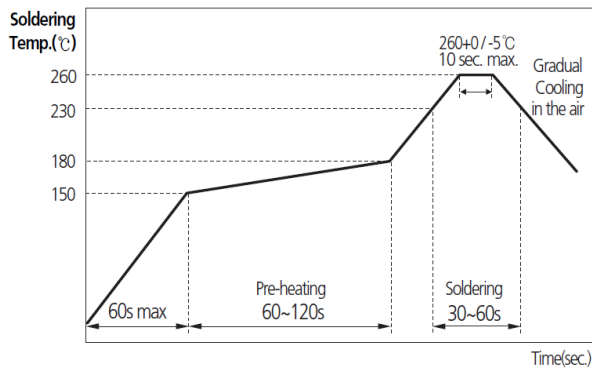
PRODUCT IDENTIFICATION

CI G 2M W 1R0 N N E
(1) **(2)** **(3)** **(4)** **(5)** **(6)** **(7)** **(8)**

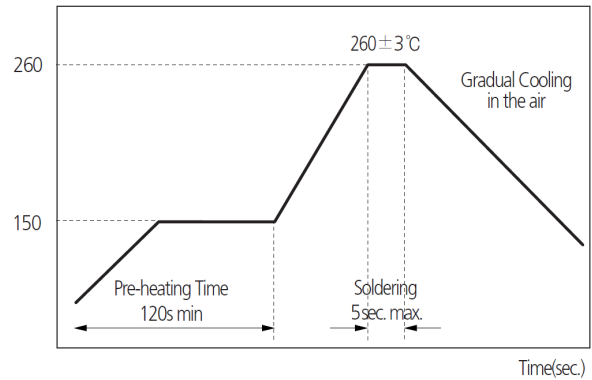
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (W:Normal Type)
- (5) Inductance (1R0:1.0uH)
- (6) Tolerance (N:±30%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	3,000

Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.